

Package outline

13-03-14

13-03-26

WLCSP9: wafer level chip-scale package; 9 bumps; body 1.36 x 1.36 x 0.51 mm (Backside Coating included) NX5P2090UK АВ ball A1 index area detail X e₁ ⊕ Ø v (M) C | A | B ⊕ Ø wM C С е e₂ В ball A1 index area 2 mm Dimensions (mm are the original dimensions) A_2 Unit Ε е e_1 у max 0.55 0.23 0.34 0.29 1.39 1.39 $nom \quad 0.51 \quad 0.20 \quad 0.31 \quad 0.26$ 1.36 1.36 0.4 8.0 8.0 0.05 0.015 0.03 min 0.47 0.17 0.29 0.23 1.33 nx5p2090uk_po References Outline European Issue date version IEC JEDEC projection JEITA

NX5P2090UK